

# **LM5146 BUCK CONVERTER PCB DESIGN**

## **REPORT**

ELECTRONIC PACKAGING, WS2024

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## Task Description:

This laboratory task involves the complete design of a prototype Printed Circuit Board (PCB) of a DC-DC Buck converter evaluation module based on the LM5146-Q1 controller IC. The task includes schematic and layout design. The specifications of the design are shown in table 1.

Table 1: Specifications

| Specification          | Description |
|------------------------|-------------|
| Input voltage range    | 15V – 80V   |
| Typical input voltage  | 48V         |
| Output voltage         | 12V         |
| Maximum output current | 6A          |
| Efficiency             | 96%         |
| Switching frequency    | 400KHz      |

## Calculations:

To correctly implement the schematic of my design, I used the application circuit 2 schematic (figure 1) from the datasheet [1] as a guide, and adjusted the values of different components as recommended. MATLAB is used to find some of the calculation results.

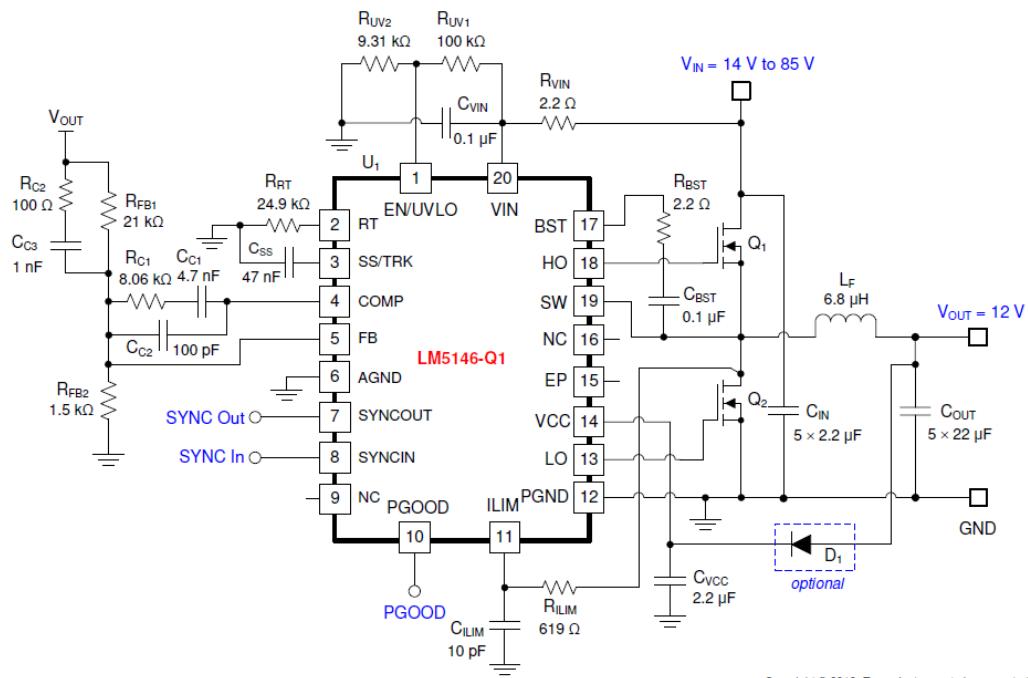


Figure 1: Application Circuit 2 from datasheet [1]

Inductor:

$$L_F = \frac{V_{OUT}}{V_{IN}} \cdot \left( \frac{V_{IN} - V_{OUT}}{\Delta I_L \cdot F_{SW}} \right)$$

Equation 1: Inductance formula [1]

```
VIN = 48;  
VOUT = 12;  
fsw = 400e3;  
IMAX = 6;  
dIL = 0.2 * IMAX;  
LF = (VOUT/VIN)*((VIN-VOUT)/(fsw*dIL))
```

LF = 1.8750e-05

Therefore, the value of LF is 18uH.

Output Capacitor ( $C_{OUT}$ ):

The output capacitor value is given by the following equation:

$$C_{OUT} \geq \frac{\Delta I_L}{8 \cdot F_{SW} \sqrt{\Delta V_{OUT}^2 - (R_{ESR} \cdot \Delta I_L)^2}}$$

Equation 2: Output Capacitor formula [1]

```
dVOUT = 0.01 * VOUT; % 1 % Tolerance  
COUT = (dIL)/(8 * fsw * sqrt((dVOUT)^2));  
  
COUT = 3.1250e-06
```

Therefore, the value of  $C_{OUT}$  is 3.12uF.

Based on the datasheet (pg.: 27), the ESR of ceramic capacitor is extremely low, so I neglected it in the calculation of output capacitor. Moreover, ignoring the ESR term in Equation 2 gives a quick estimation of the minimum ceramic capacitance necessary to meet the output ripple specification which is 2% of the maximum output current in my case. It is recommended to choose a larger output capacitance than 3.12uF, so I chose 3\*22uF.

Input Capacitance (CIN):

$$C_{IN} \geq \frac{D \cdot (1-D) \cdot I_{OUT}}{F_{SW} \cdot (\Delta V_{IN} - R_{ESR} \cdot I_{OUT})}$$

Equation 3: Input Capacitor formula [1]

D = 0.5 % datasheet page: 29

D = 0.5000

$dV_{IN} = 0.01 * V_{IN}$ ; % 1 % Tolerance  
 $C_{IN} = (D * (1-D) * I_{MAX}) / (f_{SW} * (dV_{IN}))$

CIN = 7.8125e-06

I used 4\*4.7uF in addition to 2\*10nF and 2\*100nF decoupling capacitors in parallel. My chosen capacitors are X7R rated to provide low impedance and high RMS current rating over a wide range of temperature as recommended by TI.

#### Other components:

For the other components, I used the Quickstart tool design calculator [2] to choose the values of  $R_{UV1}$ ,  $R_{UV2}$ .

The frequency adjust resistor  $R_{RT}$  I chose is 24.9Kohm for the switching frequency of 400kHz based on table 8-1 from the datasheet shown below in figure 2.

Adjust the LM5146-Q1 free-running switching frequency by using a resistor from the RT pin to AGND. The switching frequency range is from 100 kHz to 1 MHz. The frequency set resistance,  $R_{RT}$ , is governed by Equation 3. E96 standard-value resistors for common switching frequencies are given in Table 8-1.

$$R_{RT} [\text{k}\Omega] = \frac{10^4}{F_{SW} [\text{kHz}]} \quad (3)$$

Table 8-1. Frequency Set Resistors

| SWITCHING FREQUENCY<br>(kHz) | FREQUENCY SET RESISTANCE<br>(kΩ) |
|------------------------------|----------------------------------|
| 100                          | 100                              |
| 200                          | 49.9                             |
| 250                          | 40.2                             |
| 300                          | 33.2                             |
| 400                          | 24.9                             |
| 500                          | 20                               |
| 750                          | 13.3                             |
| 1000                         | 10                               |

Figure 2: Screenshot of Frequency set resistors values from the datasheet.

Placing a 2-ohm to 10-ohm resistor in series with the boot capacitor slows down the high-side MOSFET turn-on transition, serving to reduce the voltage ringing and peak amplitude at the SW

node at the expense of increased MOSFET turn on power loss(pg. 48)[1], so I added a 2.2-ohm resistor.

## Schematic design:

The figure below shows my schematic diagram. I used symbols as per the EN-60617 standard for circuit symbols [3].

## LM5146 Buck Converter

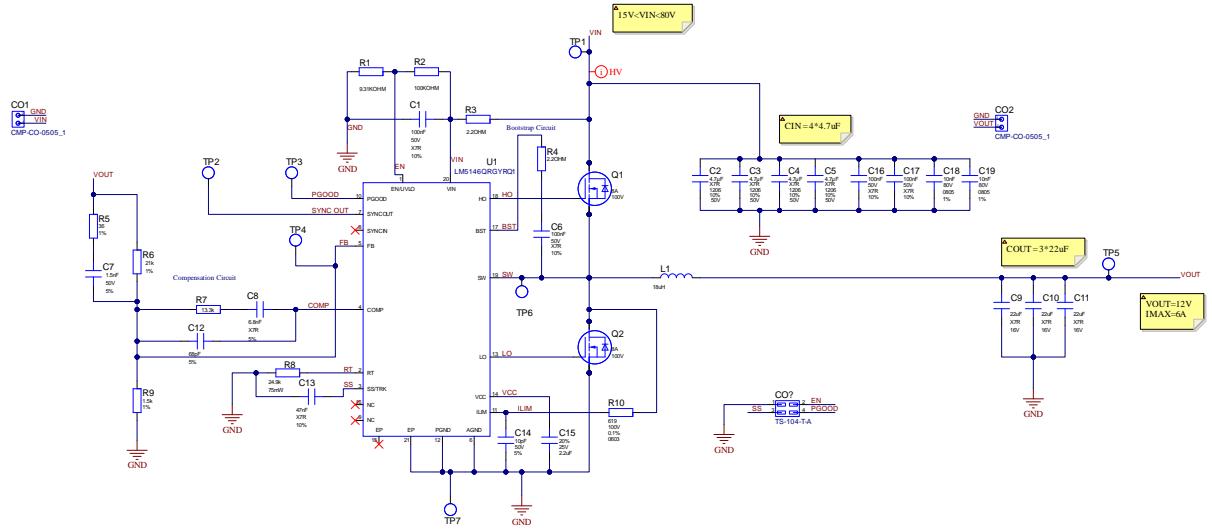


Figure 3: Schematic diagram

I have added 7 test points to take measurements of different signals and verify the functionality. Table 2 shows the test points and their net labels.

Table 2: Test points and their Net labels

| Test point | Net label |
|------------|-----------|
| TP1        | VIN       |
| TP2        | SYNC OUT  |
| TP3        | PGOOD     |
| TP4        | FB        |
| TP5        | VOUT      |
| TP6        | SW        |
| TP7        | GND       |

## Layout design:

My layout design is inspired by the layout example given in the datasheet of the LM5146-Q1, where I used copper filled polygon areas to route the components as much as possible. I mainly focused on connecting the power components with the polygons and then route the signals with tracks as shown in figure 4.

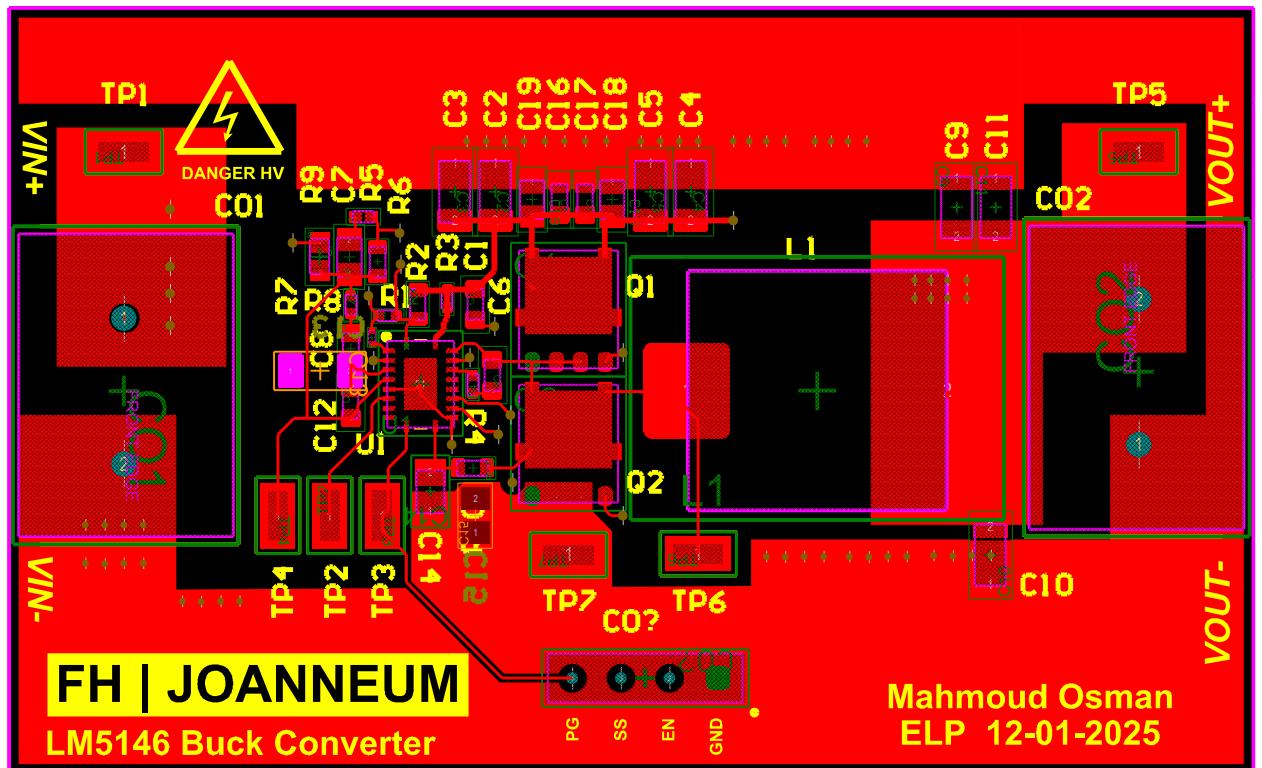


Figure 4: PCB 2D View with components- Top

In layout design rules, I chose the minimum clearance of 0.6mm for HV nets and 0.15mm according to the IPC2221 B conductor spacing requirements. [4]

Figure 5 shows my board layer stack up. It has an 8-layer stackup due to lower costs of production by eurocircuits.

| # | Name           | Material      | Type        | Weight | Thickness | Dk  | Df   | Orientation |
|---|----------------|---------------|-------------|--------|-----------|-----|------|-------------|
|   | Top Overlay    |               | Overlay     |        |           |     |      |             |
|   | Top Solder     | Solder Resist | Solder Mask |        | 0.01mm    | 3.5 |      |             |
| 1 | Top Layer      |               | Signal      | 1oz    | 0.035mm   |     |      | Top         |
|   | Dielectric 6   | PP-006        | Prepreg     |        | 0.07112mm | 4.1 | 0.02 |             |
|   | Dielectric 7   | PP-006        | Prepreg     |        | 0.07112mm | 4.1 | 0.02 |             |
| 2 | Layer 2        | CF-004        | Signal      | 1oz    | 0.035mm   |     |      | Not allowed |
|   | Dielectric 10  | Core-009      | Core        |        | 0.1016mm  | 4.5 | 0.02 |             |
| 3 | Layer 3        | CF-004        | Signal      | 1oz    | 0.035mm   |     |      | Not allowed |
|   | Dielectric 2   | PP-006        | Prepreg     |        | 0.07112mm | 4.1 | 0.02 |             |
|   | Dielectric 3   | PP-006        | Prepreg     |        | 0.07112mm | 4.1 | 0.02 |             |
| 4 | Layer 4        | CF-004        | Signal      | 1oz    | 0.035mm   |     |      | Not allowed |
|   | Dielectric 1   | FR-4          | Core        |        | 0.9mm     | 4.2 |      |             |
| 5 | Layer 5        | CF-004        | Signal      | 1oz    | 0.035mm   |     |      | Not allowed |
|   | Dielectric 4   | PP-006        | Prepreg     |        | 0.07112mm | 4.1 | 0.02 |             |
|   | Dielectric 5   | PP-006        | Prepreg     |        | 0.07112mm | 4.1 | 0.02 |             |
| 6 | Layer 6        | CF-004        | Signal      | 1oz    | 0.035mm   |     |      | Not allowed |
|   | Dielectric 11  | Core-009      | Core        |        | 0.1016mm  | 4.5 | 0.02 |             |
| 7 | Layer 7        | CF-004        | Signal      | 1oz    | 0.035mm   |     |      | Not allowed |
|   | Dielectric 8   | PP-006        | Prepreg     |        | 0.07112mm | 4.1 | 0.02 |             |
|   | Dielectric 9   | PP-006        | Prepreg     |        | 0.07112mm | 4.1 | 0.02 |             |
| 8 | Bottom Layer   |               | Signal      | 1oz    | 0.035mm   |     |      | Bottom      |
|   | Bottom Solder  | Solder Resist | Solder Mask |        | 0.01mm    | 3.5 |      |             |
|   | Bottom Overlay |               | Overlay     |        |           |     |      |             |

Figure 5 Board layer stackup

Table 3 shows the polygon pours I implemented in each layer to ensure proper thermal management and current return paths. Hence I made the VIN and VOUT planes between ground layers.

Table 3: Polygon pours

| Layer   | Polygon Pour Net(s)                |
|---------|------------------------------------|
| Layer 1 | Signals and power (GND, VIN, VOUT) |
| Layer 2 | Power (GND)                        |
| Layer 3 | Power (VIN)                        |
| Layer 4 | Power (GND)                        |
| Layer 5 | Power (VOUT)                       |
| Layer 6 | Power (GND)                        |
| Layer 7 | Power (GND)                        |
| Layer 8 | Signals and power (GND)            |

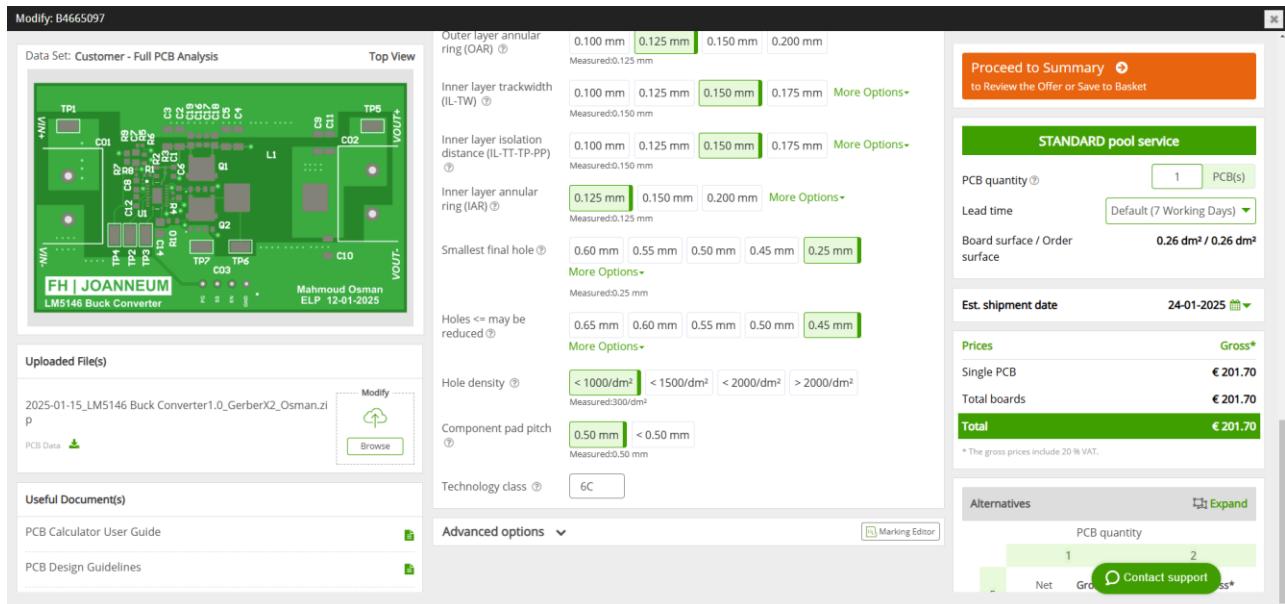


Figure 6: Price analysis

Figure 6 shows the price analysis of my board from eurocircuits PCB manufacturer[5]. It estimates the cost of my board to be €201.70 for one board of dimensions of 65mm X 40mm.

The figures below show the polygon pours of all the layers of my pcb followed by the 3D top, bottom and custom views.

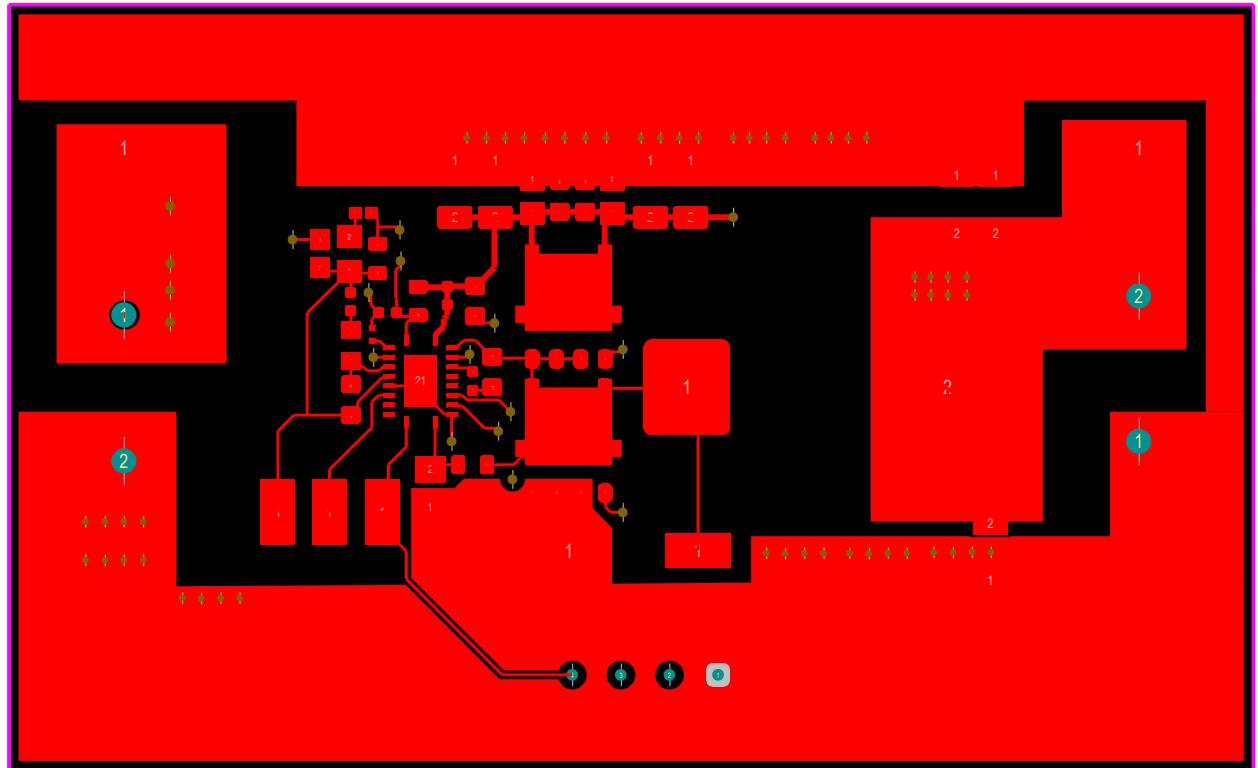


Figure 7: Layer 1 polygon pour

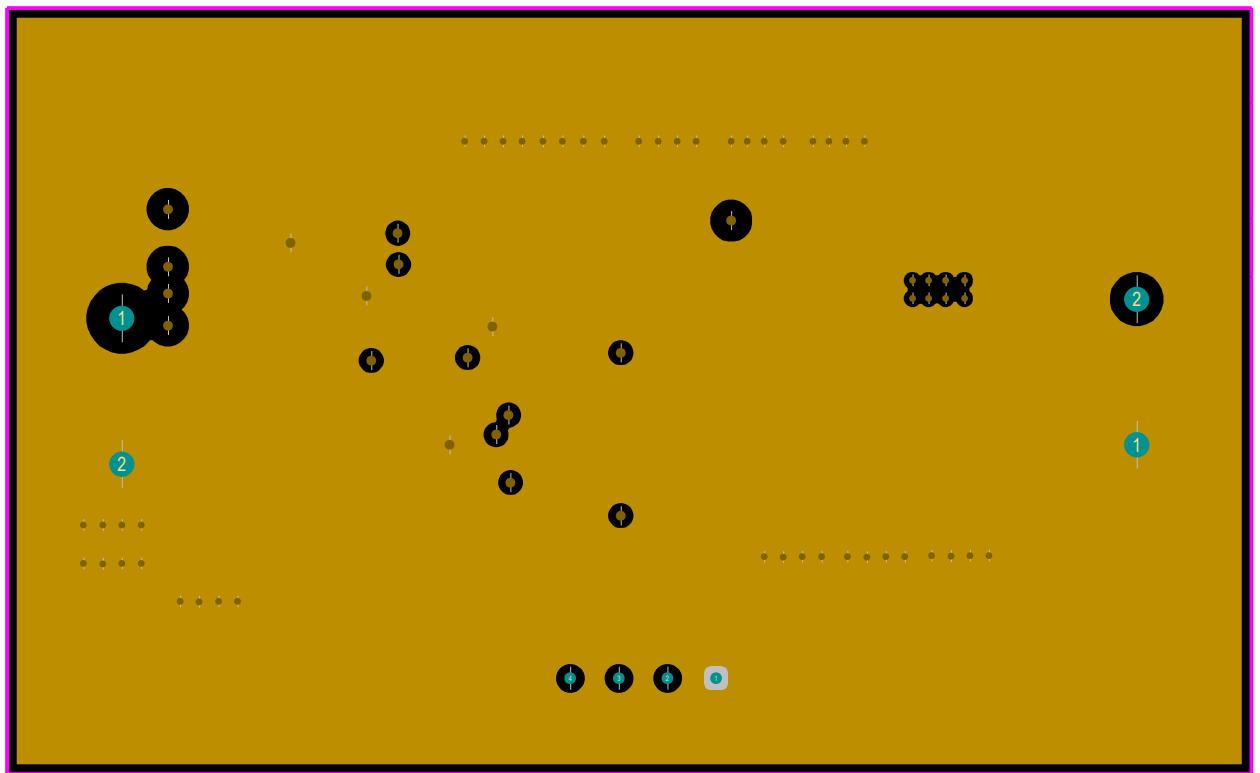


Figure 8: Layer 2 polygon pour

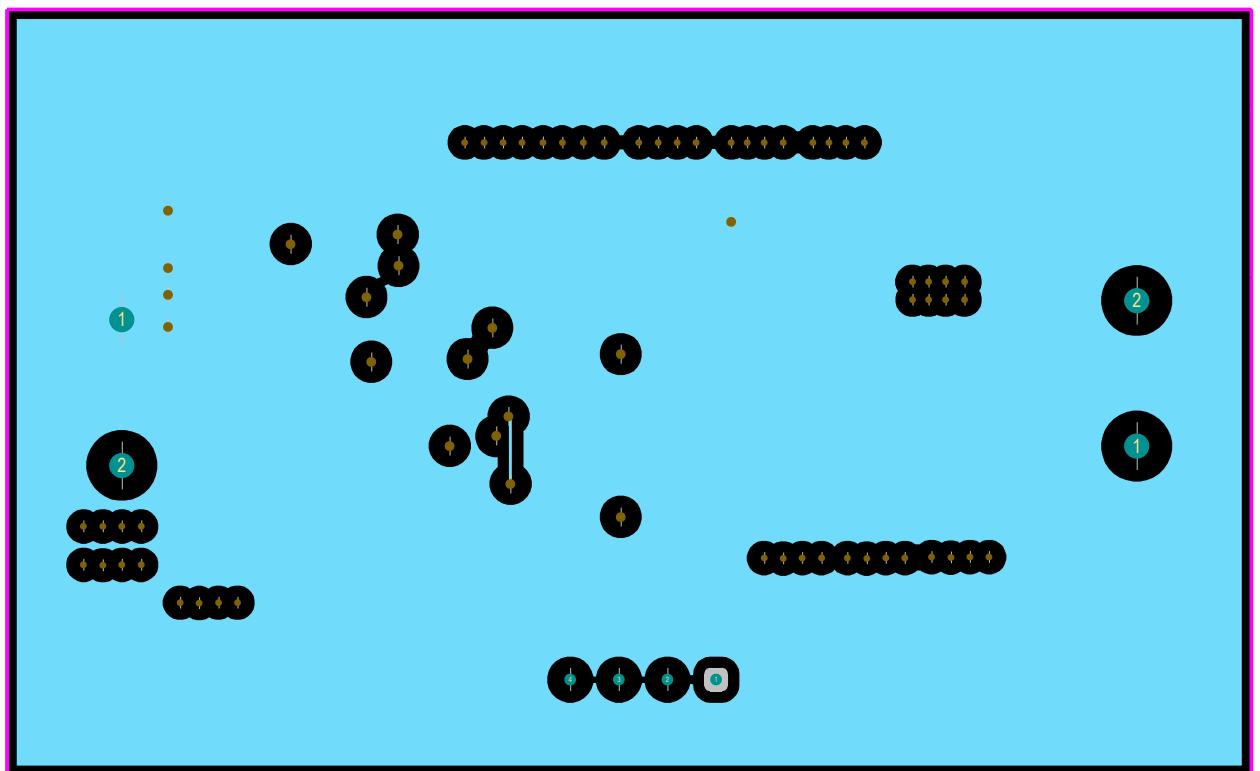


Figure 9: Layer 3 polygon pour

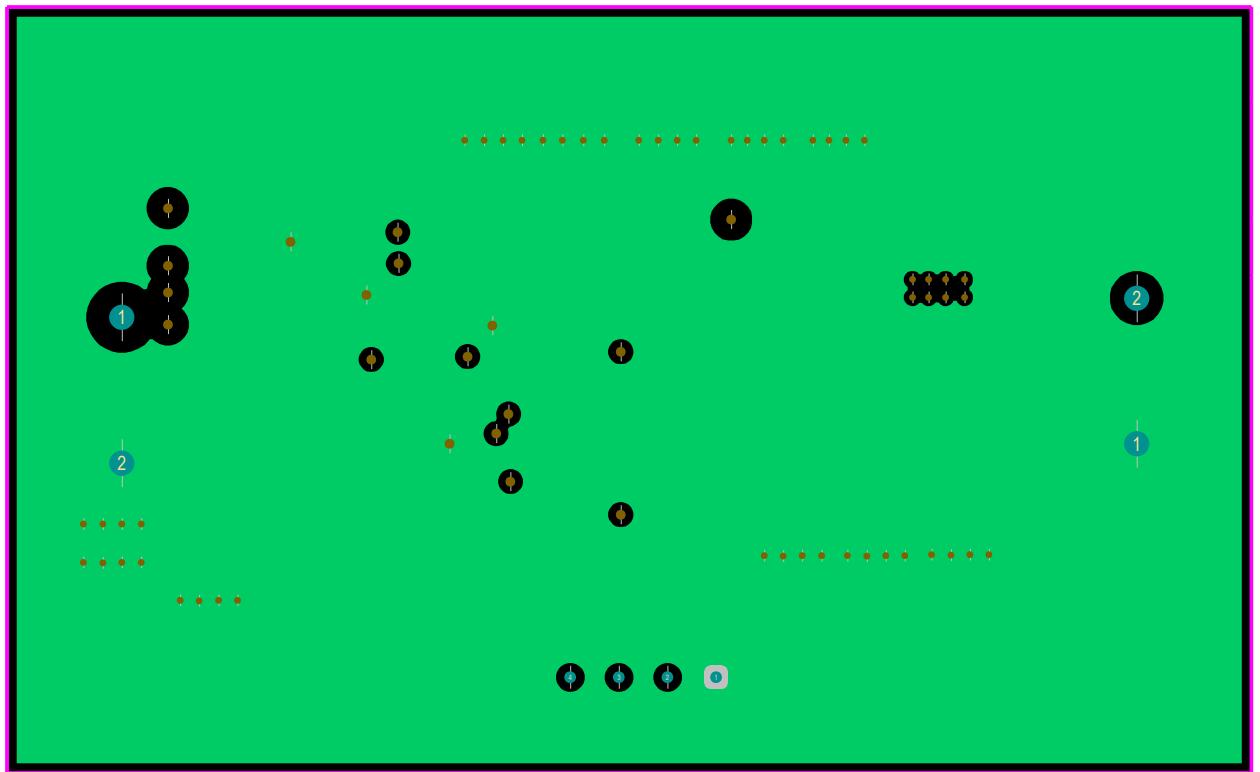


Figure 10: Layer 4 polygon pour

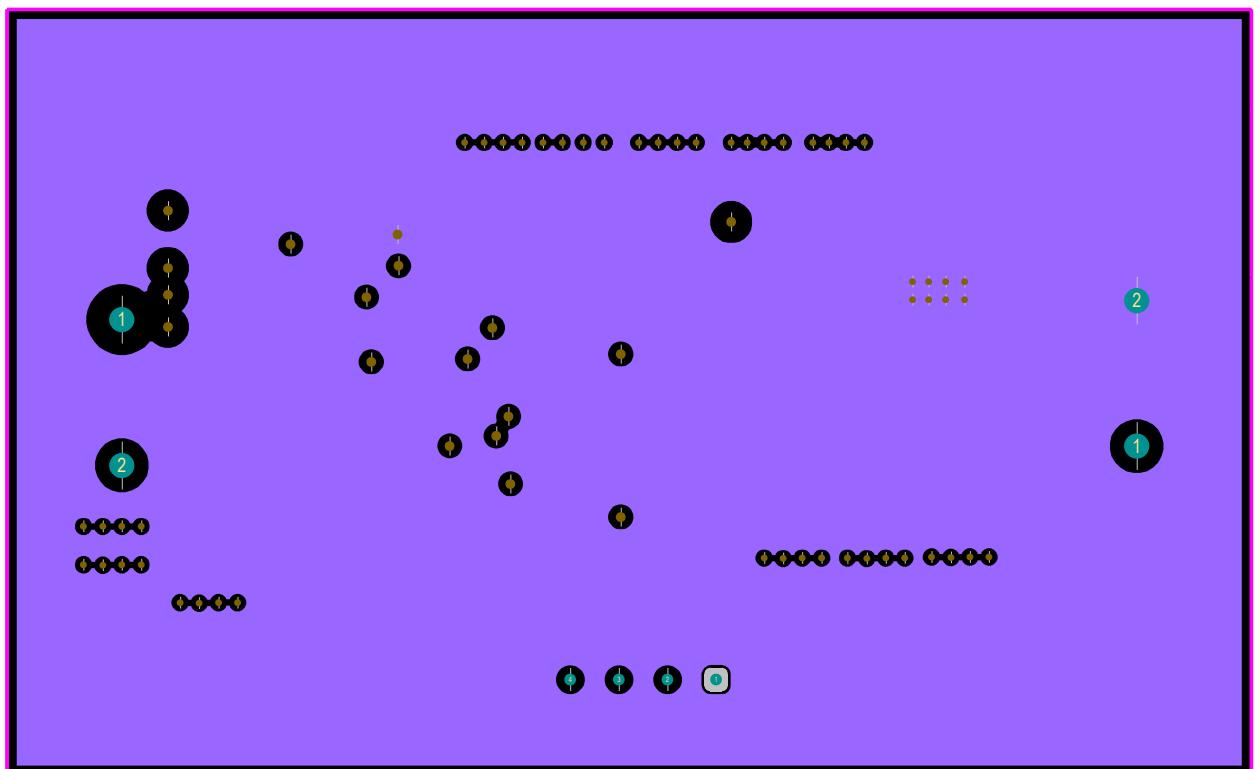


Figure 11: Layer 5 polygon pour

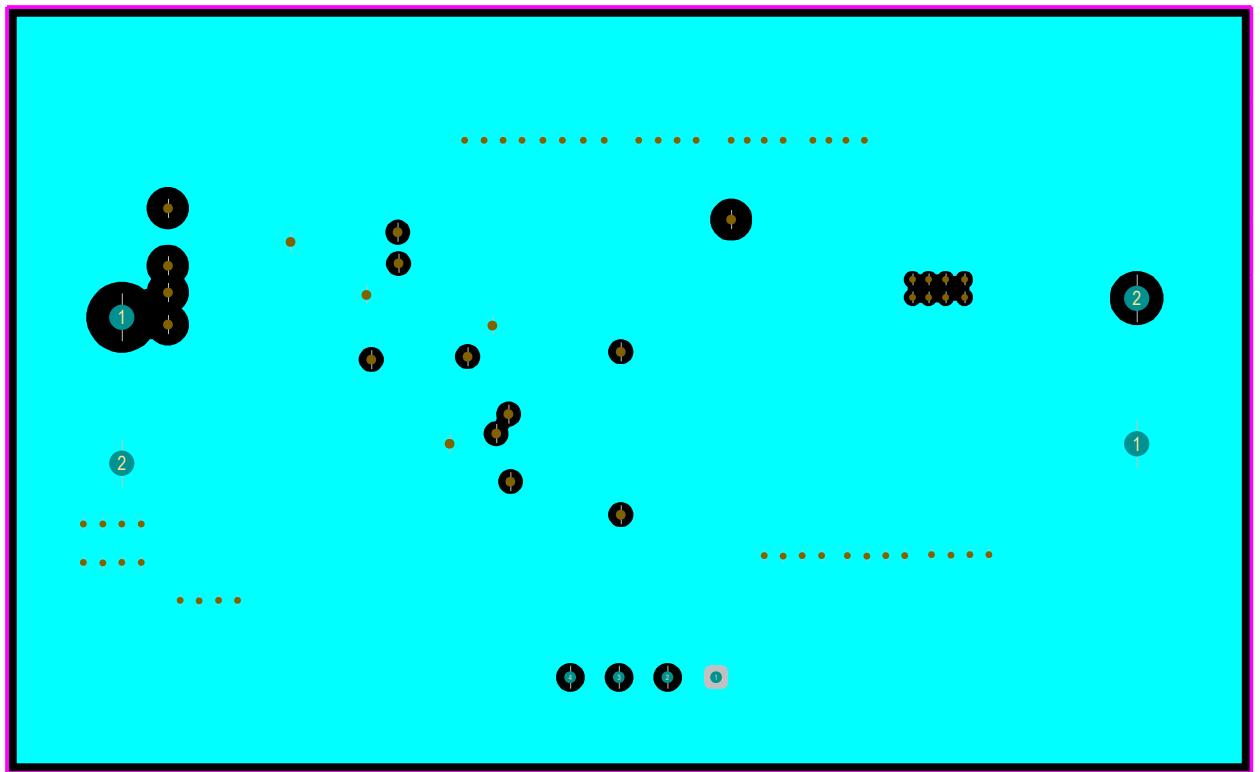


Figure 12: Layer 6 polygon pour

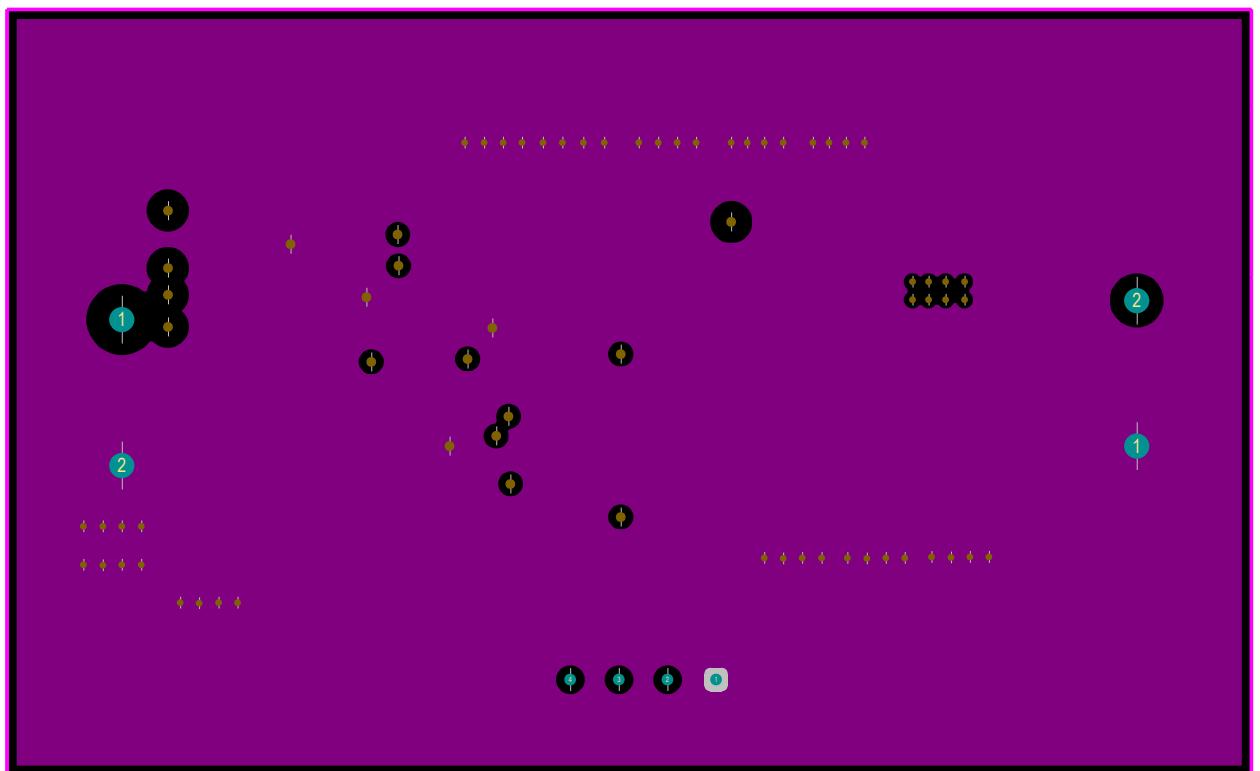


Figure 13: Layer 7 polygon pour

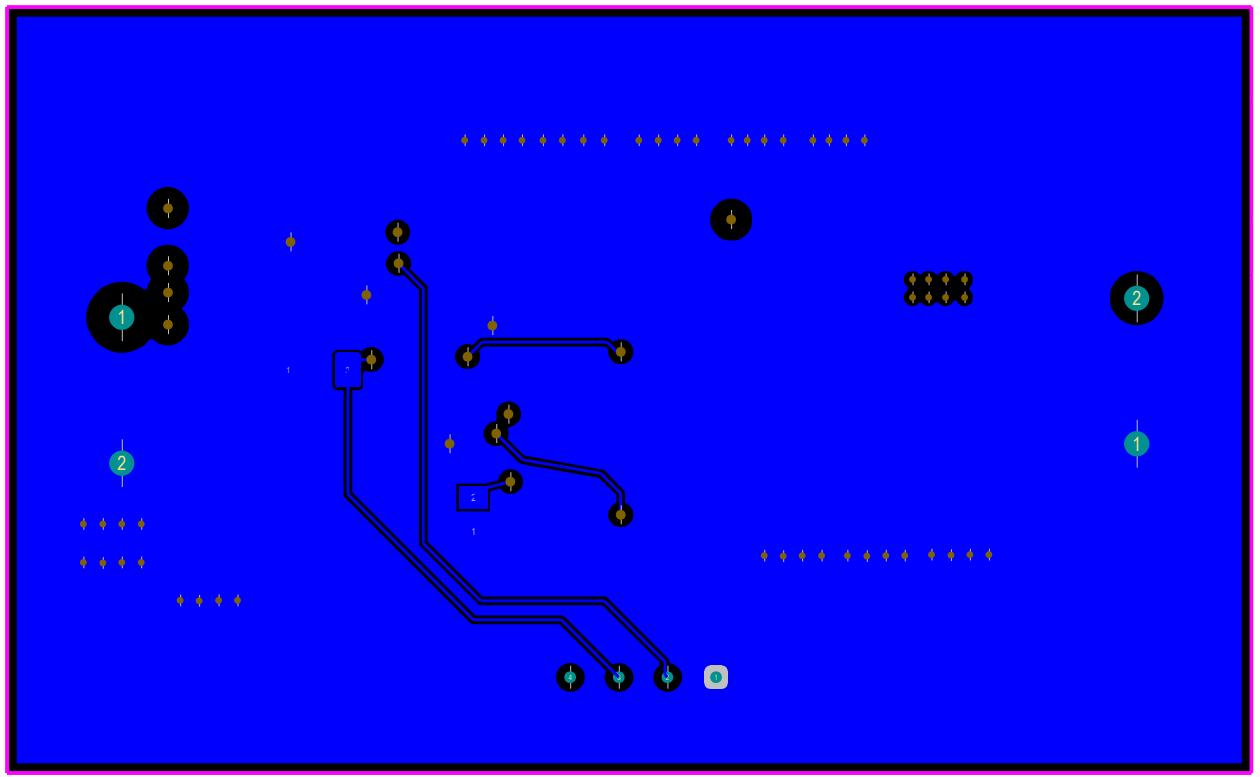


Figure 14: Layer 8 polygon pour

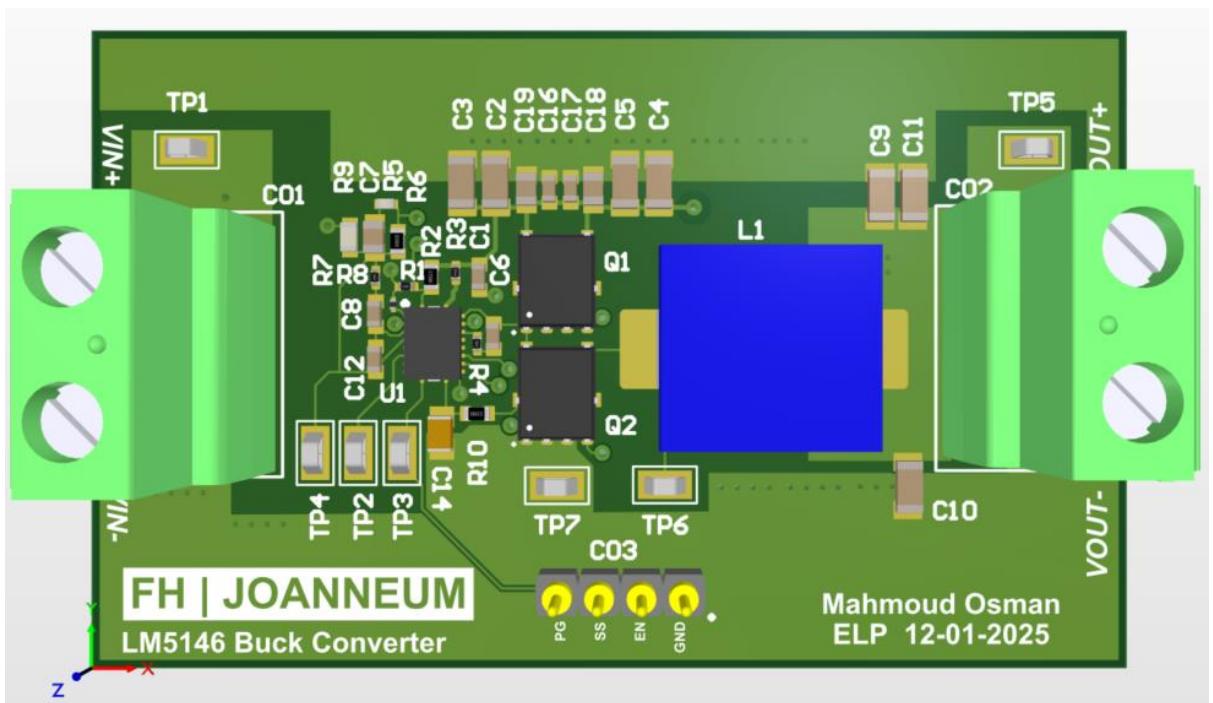


Figure 15: 3D Top View

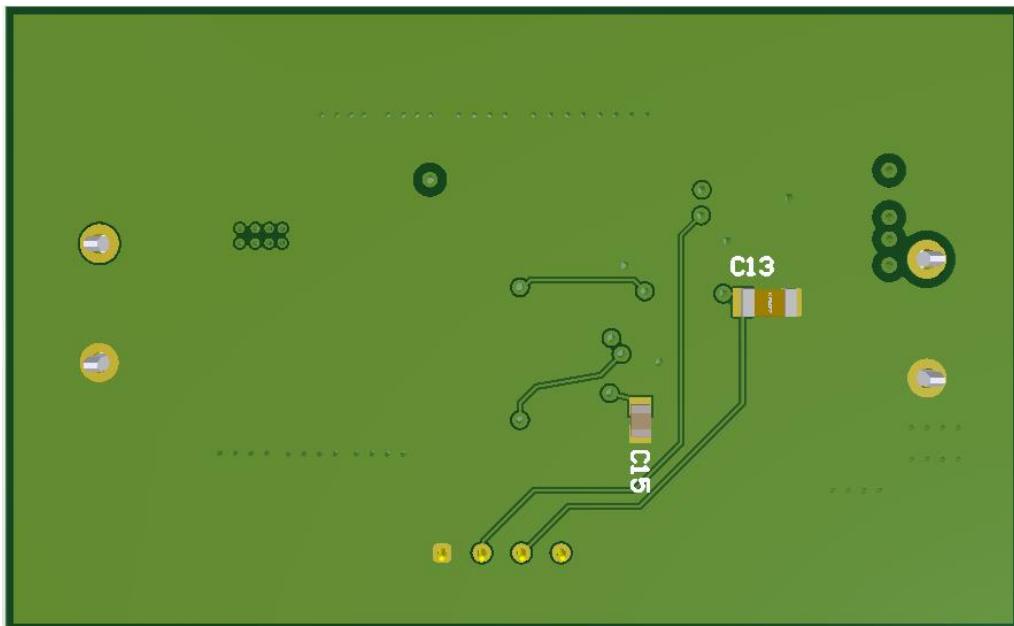


Figure 16: 3D Bottom View

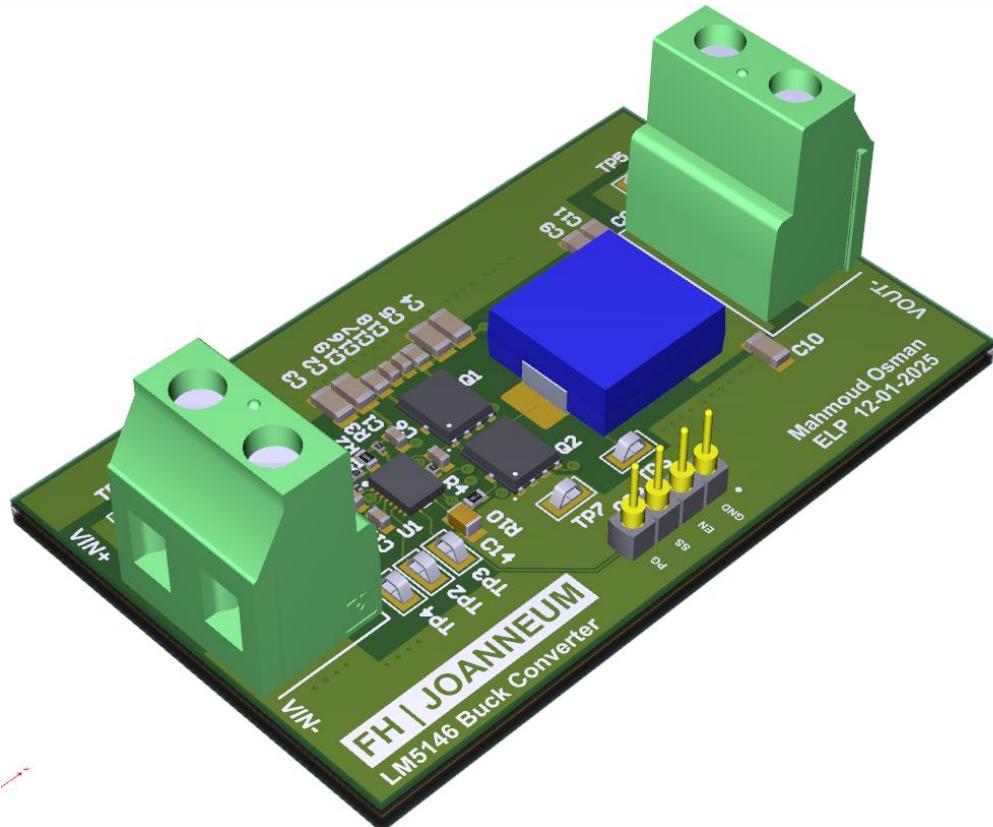


Figure 17: 3D Custom View

## References

- [1] ‘lm5146.pdf’. Accessed: Jan. 14, 2025. [Online]. Available: <https://www.ti.com/lit/ds/symlink/lm5146.pdf>
- [2] ‘LM5146DESIGN-CALC Calculation tool | TI.com’. Accessed: Jan. 14, 2025. [Online]. Available: <https://www.ti.com/tool/LM5146DESIGN-CALC>
- [3] ‘Liste der Schaltzeichen (Elektrik/Elektronik)’, *Wikipedia*. Apr. 03, 2024. Accessed: Jan. 14, 2025. [Online]. Available: [https://de.wikipedia.org/w/index.php?title=Liste\\_der\\_Schaltzeichen\\_\(Elektrik/Elektronik\)&oldid=243697134](https://de.wikipedia.org/w/index.php?title=Liste_der_Schaltzeichen_(Elektrik/Elektronik)&oldid=243697134)
- [4] ‘Using an IPC-2221 PCB Clearance Calculator for High Voltage Design’, Altium. Accessed: Dec. 29, 2024. [Online]. Available: <https://resources.altium.com/p/using-an-ipc-2221-calculator-for-high-voltage-design>
- [5] ‘PCB & PCBA prototypes and small series “right first time”’, Eurocircuits. Accessed: Jan. 15, 2025. [Online]. Available: <https://34.252.181.249/>